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IPC-A-630A

Requirements and Acceptance for Electronic Box Assemblies

If a conflict occurs between the English language and translated versions of this document, the English version will take precedence.

Developed by the 7-31J Electronic Box Assemblies Task Group of the 7-30 Product Assurance Committee of IPC

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Table of Contents

1.0	GENERAL	1-1	1.19	Handling, Preservation and Packaging	1-9
1.1	Scope	1-1	2.0	APPLICABLE DOCUMENTS	2-1
1.2	Purpose	1-1	2.1	IPC	2-1
1.3	Classification	1-1	2.2	American Society of Mechanical Engineers	2-1
1.4	Measurement Units and Applications	1-1	2.3	EIA	2-1
1.4.1	Verification of Dimensions	1-1	2.4	Electrostatic Discharge Association	2-1
1.4.2	Relationship of AWG and Wire Size.....	1-1	2.5	International Organization for Standardization ..	2-2
1.5	Definition of Requirements	1-1	2.6	International Electrotechnical Commission	2-2
1.5.1	Inspection Conditions.....	1-2	2.7	Automotive Industry Action Group	2-2
1.5.1.1	Acceptable	1-2	2.8	American Welding Society	2-2
1.5.1.2	Defect.....	1-2	2.9	ASTM	2-3
1.5.1.2.1	Disposition	1-2	2.10	GEIA	2-3
1.5.1.3	Process Indicator	1-2	2.11	Aerospace Industry Association	2-3
1.5.1.4	Conditions Not Specified.....	1-2	2.12	International Aerospace Quality Group	2-3
1.5.1.5	Uncommon or Specialized Designs.....	1-3	2.13	Society of Automotive Engineers (SAE)	2-3
1.5.2	Material and Process Nonconformance	1-3	3.0	GENERAL REQUIREMENTS	3-1
1.6	Process Control Requirements	1-3	3.1	Wire Preparation	3-1
1.6.1	Statistical Process Control (SPC).....	1-3	3.2	Soldering	3-1
1.7	Order of Precedence	1-4	3.3	Crimping	3-1
1.8	Terms and Definitions	1-4	3.4	Splices	3-1
1.8.1	Clause References	1-4	3.5	Fiber Optic Cables	3-1
1.8.2	Appendices.....	1-4	3.6	Coaxial Cables	3-1
1.9	Requirements Flowdown	1-4	3.7	General Damage	3-1
1.10	Personnel Proficiency	1-4	4.0	ENCLOSURE FABRICATION	4-1
1.11	Acceptance Requirements	1-4	4.1	Surface Types	4-1
1.12	Inspection	1-4	4.2	Inspection	4-1
1.12.1	Sampling.....	1-4	4.3	Sheet Metal Processing	4-1
1.12.2	Lighting.....	1-4	4.3.1	Sheet Metal Minimum Bend Radius.....	4-2
1.12.3	Magnification Aids	1-5	4.4	Casting Surface	4-3
1.13	Facilities	1-5	4.5	Welding and Brazing Specifications	4-4
1.13.1	Field Assembly Operations.....	1-5	4.5.1	Procedure Qualification	4-4
1.14	Electrostatic Discharge (ESD) Control Program ..	1-6	4.5.2	Personnel Qualification	4-4
1.14.1	ESD Packaging.....	1-6	4.6	Helical-Coil Inserts	4-4
1.15	Tools and Equipment	1-6	4.7	Rivets	4-5
1.15.1	Control.....	1-6	4.7.1	Material Preparation	4-5
1.15.2	Calibration	1-6	4.7.2	Conventional Rivets	4-6
1.16	Materials and Processes	1-7	4.7.2.1	Driven/Shop Formed Head.....	4-6
1.17	Electrical Clearance	1-7	4.7.2.1.1	Dimples	4-6
1.18	Foreign Object Debris (FOD)	1-9			

Table of Contents (cont.)

4.7.2.1.2	Diameter and Height.....	4-6	6.4.3	Application of Materials	6-2
4.7.2.1.3	Malformed Rivets	4-7	6.4.4	Acceptance Criteria for Encapsulants.....	6-3
4.7.2.1.4	Concentricity	4-7	6.4.5	Acceptance Criteria for Sealants	6-6
4.7.2.1.5	Cracks.....	4-8	6.5	Application of Thermal Compounds and Pads ..	6-7
4.7.2.2	Manufactured Head.....	4-9	6.5.1	Surface Preparation	6-7
4.7.2.2.1	Marred Heads	4-9	6.5.2	Masking.....	6-7
4.7.2.2.2	Flattened Heads	4-9	6.5.3	Application of Thermal Compound.....	6-8
4.7.2.2.3	Open Heads (Gapping).....	4-10	6.5.4	Thermal Compound Application Process Development Guidelines.....	6-9
4.7.2.2.4	Flush Rivet Head Height.....	4-10	6.5.5	Application of Thermal Pads	6-11
4.7.3	Blind Rivets	4-11	6.5.6	Workmanship – Thermal Compound	6-11
4.7.3.1	Open Heads (Gapping).....	4-11	6.5.6.1	Prior to Mating Surfaces	6-12
4.7.3.2	Flush Rivets	4-11	6.5.6.2	After Component Surfaces Have Been Mated..	6-13
4.7.3.3	Hollow Type Rivets.....	4-12	6.5.7	Thermal Pads.....	6-14
4.7.4	Sheet and Hole Requirements	4-13	7.0	INSTALLATION	7-1
4.7.4.1	Sheet Deformation.....	4-13	7.1	Installation of Heat Exchangers and Piping	7-1
4.7.4.2	Countersinks	4-14	7.1.1	Heat Exchangers.....	7-1
4.7.4.3	Misalignment.....	4-14	7.1.2	Piping	7-1
4.7.5	Specialized Rivets	4-14	7.2	Installation of Flexible and Rigid-Flex Printed Board Assemblies	7-2
5.0	SURFACE FINISHES	5-1	7.3	Installation of Printed Board Assemblies	7-4
5.1	Application	5-1	7.4	Connector Installation	7-5
5.2	Curing and Adhesion.....	5-1	7.5	Threaded Fastener Installation.....	7-5
5.3	Performance Requirements	5-1	7.5.1	Process.....	7-6
5.4	Inspection	5-1	7.5.1.1	Torque	7-7
5.4.1	Appearance.....	5-1	7.5.1.1.1	Sequence/Torque Pattern.....	7-7
5.4.2	Color and Gloss	5-2	7.5.2	Tooling and Equipment	7-8
5.4.2.1	Spectrophotometric Analysis.....	5-2	7.5.3	Materials Applied to the Fastener System.....	7-8
5.4.2.2	Visual	5-2	7.6	Hardware Installation	7-9
5.4.3	Cosmetic Flaws.....	5-2	7.7	Electrical Bonding	7-11
5.4.4	Inorganic Coating Inspection.....	5-3	7.8	Installation of Heatsinks	7-11
5.4.5	Organic Coating Inspection	5-3	7.8.1	Heatsink Hardware	7-11
5.4.5.1	Complex Shapes.....	5-4	8.0	CABLE/HARNESS INSTALLATION	8-1
5.5	Touch-Up of Surface Finish.....	5-6	8.1	General.....	8-1
6.0	APPLICATION OF NON-METALLIC MATERIALS FOR ASSEMBLY	6-1	8.2	Cable/Wire Harness Protective Coverings	8-2
6.1	Cleaning	6-1	8.2.1	Braid – Prewoven.....	8-2
6.2	Foamed Polymers	6-1	8.2.2	Sleeving/Shrink Tubing	8-4
6.3	Adhesive Bonding	6-1	8.2.2.1	Sealant	8-5
6.4	Encapsulants and Sealants	6-1	8.2.3	Spiral Plastic Wrap (Spiral Wrap Sleeving)	8-6
6.4.1	Surface Preparation	6-2	8.2.4	Split and Unsplit Wire Loom Tubing	8-7
6.4.2	Material Preparation	6-2			

Table of Contents (cont.)

8.2.5	Adhesive or Non-Adhesive Barrier and Conductive Tapes	8-7	8.12.1	Bending	8-42
8.2.6	Sleeving and Boots	8-8	8.12.2	Attachment	8-42
8.2.6.1	Position	8-8	8.13 Shield Termination		8-43
8.2.6.2	Bonding	8-9	8.13.1	Shield Jumper Wire	8-43
8.3 Securing		8-11	8.13.1.1	Attached Lead – Solder	8-43
8.3.1	Tie Wrap/Lacing Application	8-11	8.13.1.2	Attached Lead – Crimp	8-47
8.3.1.1	Tightness	8-16	8.13.1.3	Shield Braid – Woven	8-48
8.3.1.2	Damage	8-17	8.13.1.4	Shield Braid – Combed and Twisted	8-48
8.3.1.3	Spacing	8-17	8.13.2	Unterminated Shield	8-49
8.3.2	Breakouts	8-18	8.13.2.1	Shield Not Folded Back	8-50
8.3.2.1	Individual Wires	8-18	8.13.2.2	Shield Folded Back	8-50
8.3.2.2	Spacing	8-19	8.13.3	Connector	8-51
8.3.3	Routing	8-21	8.13.3.1	Shrink	8-51
8.3.3.1	Wire Crossover	8-21	8.13.3.2	Crimp	8-52
8.3.3.2	Bend Radius	8-22	8.13.3.3	Shield Jumper Wire Attachment	8-54
8.3.3.3	Coaxial Cable	8-24	8.13.3.4	Soldered	8-55
8.3.3.4	Unused Wire Termination	8-25	8.14 Conduit (Shielding)		8-56
8.3.3.4.1	Shrink Sleeving	8-25	8.15 Shrink Tubing – Conductive Lined		8-56
8.3.3.4.2	Flexible Sleeving	8-26	9.0 CONNECTORIZATION		9-1
8.3.3.5	Ties Over Splices and Ferrules	8-27	9.1 Hardware Mounting		9-1
8.3.4	Broom Stitching	8-28	9.1.1	Jackpost – Height	9-1
8.3.5	Intersecting Wire Bundles/Cables	8-28	9.1.2	Jackscrews – Protrusion	9-2
8.4 Hardware Installation – Threaded Fasteners ..		8-28	9.1.3	Retaining Clips	9-3
8.4.1	Wires	8-29	9.1.4	Connector Alignment	9-4
8.4.1.1	Solid Wires	8-29	9.2 Strain Relief		9-5
8.4.1.2	Stranded Wires	8-31	9.2.1	Clamp Fit	9-5
8.4.2	Safety Wiring	8-32	9.2.2	Wire Dress	9-7
8.4.3	Safety Cable	8-34	9.2.2.1	Straight Approach	9-7
8.5 Stress Relief		8-34	9.2.2.2	Side Approach	9-8
8.6 Wire Dress		8-35	9.3 Connector Damage		9-9
8.7 Service Loops		8-36	9.3.1	Criteria	9-9
8.8 Clamping		8-37	9.3.2	Limits – Hard Face Mating Surface	9-10
8.9 Shield Termination – Splicing Prewoven		8-37	9.3.3	Limits – Soft Face Mating Surface or Rear Seal Area	9-11
8.9.1	Soldered	8-38	9.3.4	Contacts	9-12
8.10 Raceways		8-39	9.4 Installation of Contacts and Sealing Plugs into Connectors		9-13
8.11 Grommets		8-40	9.4.1	Installation of Contacts	9-13
8.11.1	Wire/Cable/Bundle – Sealing Not Required ..	8-40	9.4.2	Installation of Sealing Plugs	9-15
8.11.2	Wire/Cable/Bundle – Sealing Required	8-41	9.5 Center Pin		9-16
8.12 Terminal Lugs		8-42			

Table of Contents (cont.)

9.5.1	Position	9-16	Table 4-1	Inspection Criteria for Metal Processing.....	4-1
9.5.2	Damage	9-17	Table 4-2	Minimum Bend Radius Requirements for Aluminum Alloys	4-2
9.6	Mechanical Test Methods – Contact Retention Verification	9-17	Table 4-3	Minimum Bend Radius Requirements for 300 Series Stainless Steel.....	4-2
10.0	MARKING/LABELING	10-1	Table 4-4	Welding and Brazing Reference Documents ...	4-4
10.1	Marking Requirements.....	10-1	Table 4-5	Identification Markings on Conventional/Solid Rivets	4-5
10.1.1	General.....	10-1	Table 4-6	Dimensions of Driven/Shop Formed Head (mm [in]).....	4-6
10.1.2	Surface Preparation.....	10-1	Table 4-7	A-Max Dimension by Rivet Size.....	4-11
10.1.3	Location.....	10-2	Table 5-1	Inspection Criteria for Inorganic Coatings.....	5-3
10.1.4	Curing and Adhesion	10-2	Table 5-2	Inspection Criteria for Organic Coatings	5-3
10.1.5	Content, Legibility and Permanency.....	10-2	Table 7-1	Minimum Bend Ratio for Flexible Printed Board Assemblies	7-2
10.2	Internal Assemblies and Subassemblies.....	10-2	Table 8-1	Minimum Bend Radius Requirements.....	8-22
11.0	TESTING/VERIFICATION	11-1	Table 8-2	Bend Radius Requirements for Harness Assemblies with Optical Fiber or Optical Cable	8-23
APPENDIX A	Terms and Definitions.....	A-1	Table 8-3	Minimum Swaged Ferrule Pull-Off Load.....	8-34
Tables					
Table 1-1	Magnification Aids – Wire Applications	1-5			
Table 1-2	Magnification Aids – Other Applications	1-5			

1.0 GENERAL

1.1 Scope This standard provides the requirements and acceptance criteria for electronic box assemblies.

1.2 Purpose This standard has been written to direct the Manufacturers and end Users of electronic box assemblies of electrical and electronic equipment to understand the best practices to meet requirements, ensuring the reliability and function of the end item assembly for its intended design life.

An electronic box is also known as a top level assembly, higher level assembly (HLA), functional unit, drawer, cabinet, housing, line replaceable unit (LRU) or other designation. An electronic box typically consists of a combination of assemblies, cable and wire harness assemblies, and other electronics and/or mechanical components, and is typically tested as a functional unit. The box includes the necessary mechanical and structural elements to protect and integrate the assembly into a finished system.

1.3 Classification This standard recognizes that electrical and electronic assemblies are subject to classification by intended end-item use. Three general end-product Classes have been established to reflect differences in manufacturability, complexity, functional performance requirements and verification (inspection/test) frequency.

Use of this standard requires establishing the Class to which the product belongs. The User has the responsibility to identify the Product Class. If the User does not establish and document the Product Class, it is acceptable for the Manufacturer to do so.

Class 1 – General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

Class 2 – Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically the end-use environment would not cause failures.

Class 3 – High Performance Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment should function when required such as life support or other critical systems.

1.4 Measurement Units and Applications All dimensions and tolerances, as well as other forms of measurement (temperature, weight, etc.) in this standard are expressed in SI (System International) units with Imperial English equivalent dimensions provided in brackets. Dimensions and tolerances use millimeters as the main form of dimensional expression; micrometers are used when the precision required make millimeters too cumbersome. Celsius is used to express temperature. Weight is expressed in grams. Conductor sizes are expressed in American Wire Gauge (AWG).

1.4.1 Verification of Dimensions Unless specifically required herein, actual measurement of specific part mounting and determination of percentages are not required except for referee purposes. For the purposes of determining conformance to this specification, all specified limits in this standard are absolute limits as defined in ASTM E29.

1.4.2 Relationship of AWG and Wire Size AWG numbers increase as the conductor diameter decreases. For example, 22 AWG has a conductor with a smaller diameter than 11 AWG. In this standard, when “smaller than” or “larger than” is used in reference to wire size, it is referencing the wire diameter and not the wire gauge.

1.5 Definition of Requirements The words **shall** and **shall not** are used in the text of this document wherever there is a requirement for materials, process control, or acceptance of an electronic box assembly.

Where the words **shall** or **shall not** lead to a hardware defect for at least one Class, the requirements for each Class are in brackets next to the requirement.

N = No requirement has been established for this Class

A = Acceptable

P = Process Indicator

D = Defect